

IN THE SPECIFICATION

After the title and before paragraph [0009], insert

FIELD OF THE INVENTION

Page 1, [0001] revise as follows:

- I. The invention relates to a magnet configuration ~~according to the preamble of patent claim 1.~~

Page 1, after paragraph [0001] insert

BACKGROUND OF THE INVENTION

Page 1, paragraph [0001] revise as follows:

In a sputter installation a plasma is generated in a vacuum ~~in vacuo~~ in a sputter chamber. Positive ions of the plasma are attracted by the negative potential of a cathode, which is provided with a so-called target. The positive ions impinge on this target and knock out small particles, which can become deposited on a substrate. Knocking out these particles is referred to as "sputtering". The plasma is comprised of gases which, in the case of non-reactive sputtering, can be inert gases, for example argon. In reactive sputtering, for example, oxygen is utilized alone or together with an inert gas.

Page 3, before paragraph [0008], insert

OBJECT AND SUMMARY OF THE INVENTION

Page 3, paragraph [0009], This objective is attained according to the present invention ~~through the characteristics of patent claims 1 or 2.~~

Page 3, paragraph [0011]

Embodiment examples of the invention are depicted in the drawing and will be described in further detail in the following. ~~In the drawing depict:~~

Page 3, after paragraph [0011] insert

BRIEF DESCRIPTION OF THE DRAWINGS

Page 4, after paragraph [0018], insert

DETAILED DESCRIPTION

Page 10, before claim 1, delete

~~Patents Claims~~ and insert It is claimed: